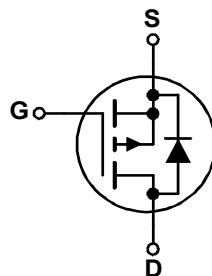
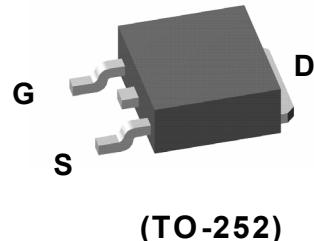


## 40V P-Channel PowerTrench® MOSFET

**-40V, -45A, 14mΩ**

### Features

- Max  $r_{DS(on)}$  = 14mΩ at  $V_{GS} = -10V$ ,  $I_D = -45A$
- Max  $r_{DS(on)}$  = 20mΩ at  $V_{GS} = -4.5V$ ,  $I_D = -30A$



Drain-Source Voltage	$V_{DS}$	-4	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	-45	A
Drain Current-Continuous( $T_C=100^\circ\text{C}$ )	$I_D(100^\circ\text{C})$	-25	A
Pulsed Drain Current	$I_{DM}$	-50	A
Maximum Power Dissipation	$P_D$	80	W
Derating factor		0.53	W/°C
Single pulse avalanche energy <sup>(Note 5)</sup>	$E_{AS}$	544	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 175	°C

### Notes

- Package limited.
- Pulse test; pulse width  $\leq 300 \mu\text{s}$ , duty cycle  $\leq 2 \%$ .
- When mounted on 1" square PCB (FR4 material).
- Parametric verification ongoing.

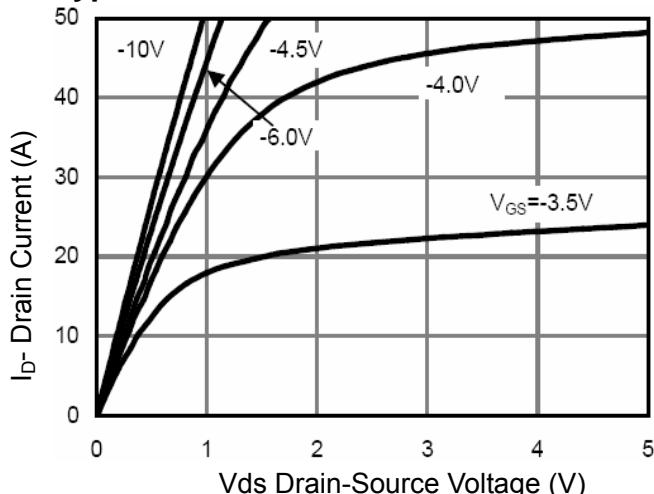
### Thermal Characteristic

Thermal Resistance,Junction-to-Case <sup>(Note 2)</sup>	R <sub>θJC</sub>	1.88	°C/W
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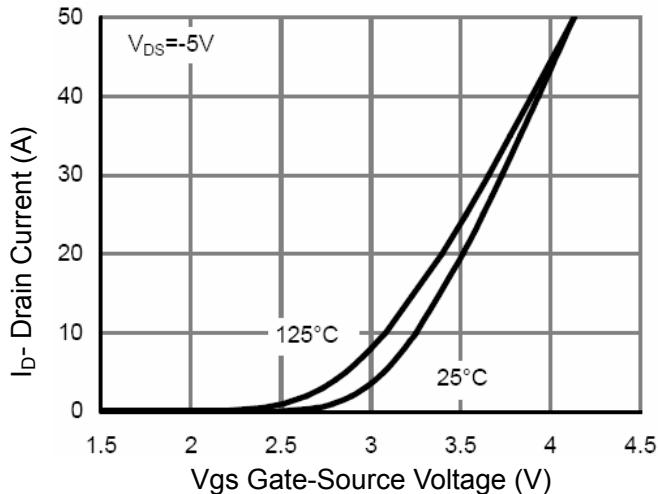
### Electrical Characteristics (T<sub>C</sub>=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-40	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-40V, V <sub>GS</sub> =0V	-	-	-1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>On Characteristics</b> <sup>(Note 3)</sup>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-1.5	-1.9	-3.0	V
Drain-Source On-State Resistance	R <sub>DSON</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-45A	-	15		mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =-5V, I <sub>D</sub> =-20A	34	-	-	S
<b>Dynamic Characteristics</b> <sup>(Note 4)</sup>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V, F=1.0MHz	-	2960	-	PF
Output Capacitance	C <sub>oss</sub>		-	370	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	310	-	PF
<b>Switching Characteristics</b> <sup>(Note 4)</sup>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =-20V, I <sub>D</sub> =-20A V <sub>GS</sub> =-10V, R <sub>G</sub> =3Ω	-	10	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	18	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	38	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	24	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =-20, I <sub>D</sub> =-20A, V <sub>GS</sub> =-10V	-	72		nC
Gate-Source Charge	Q <sub>gs</sub>		-	14		nC
Gate-Drain Charge	Q <sub>gd</sub>		-	15		nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <sup>(Note 3)</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =-20A	-		-1.2	V
Diode Forward Current <sup>(Note 2)</sup>	I <sub>S</sub>		-	-	-40	A
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, IF = - 20A di/dt = -100A/μs <sup>(Note 3)</sup>	-	40		nS
Reverse Recovery Charge	Q <sub>rr</sub>		-	42		nC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

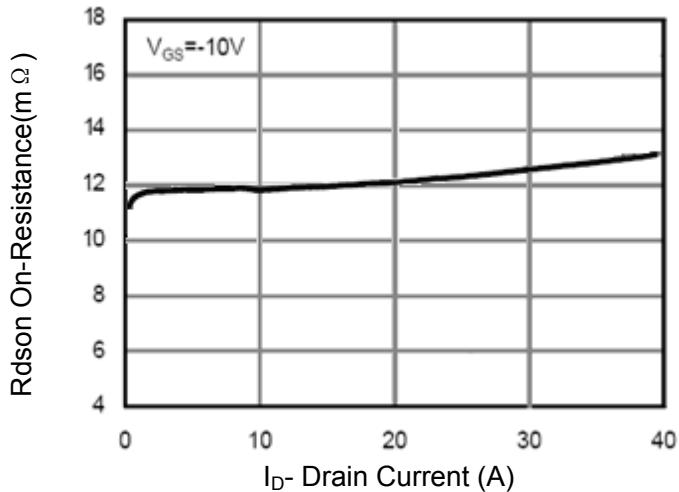
### Typical Electrical and Thermal Characteristics (Curves)



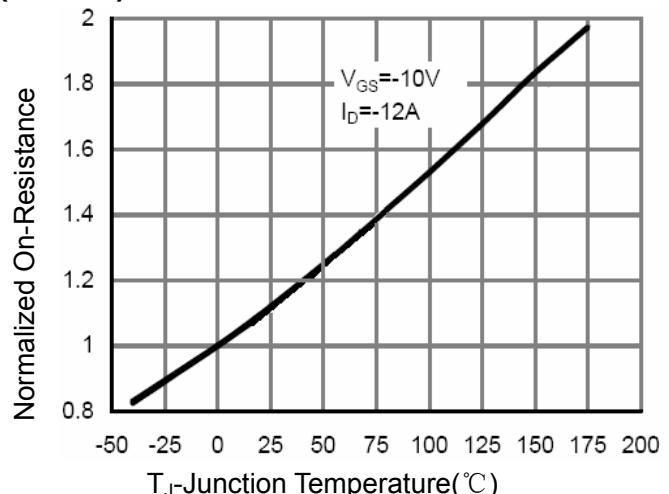
**Figure 1 Output Characteristics**



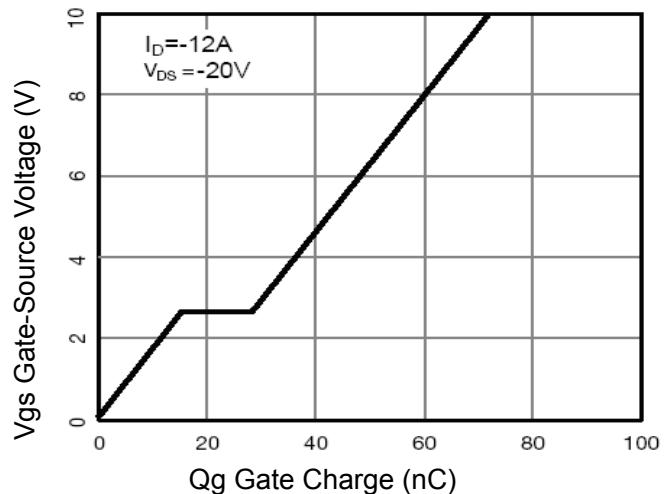
**Figure 2 Transfer Characteristics**



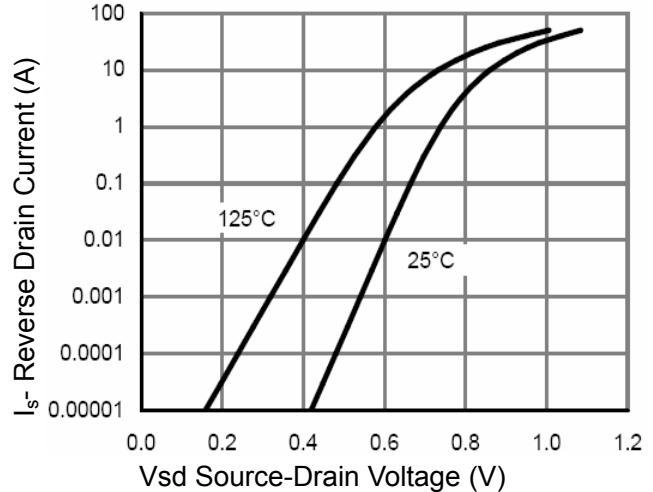
**Figure 3 Rdson- Drain Current**



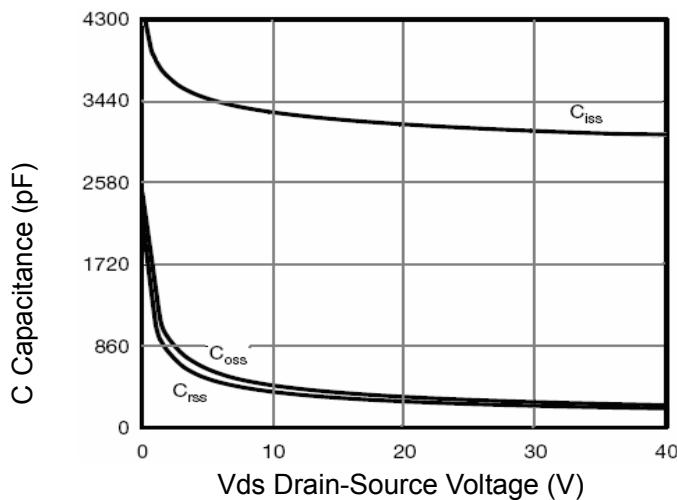
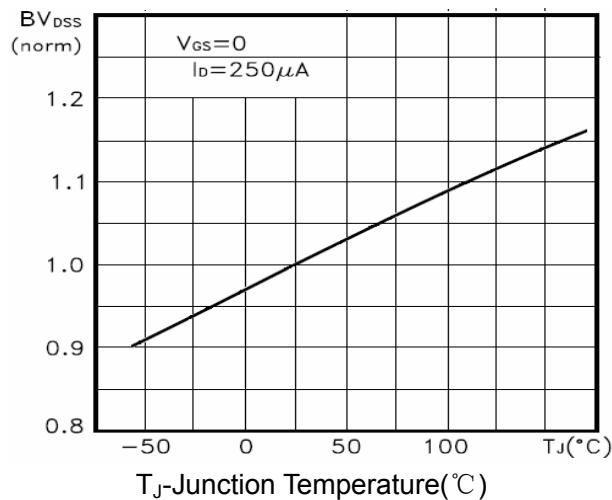
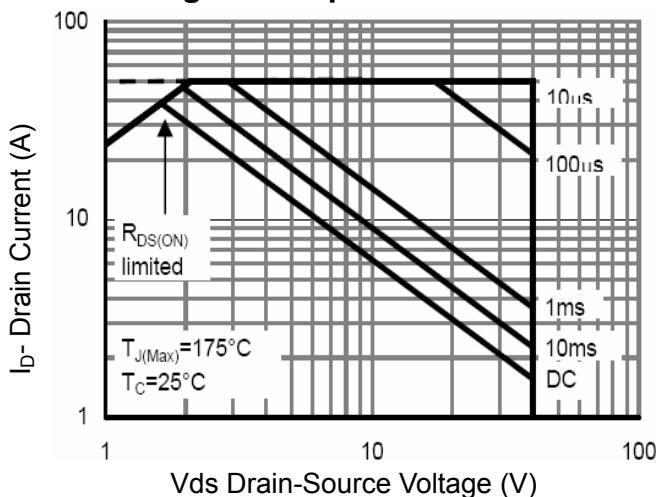
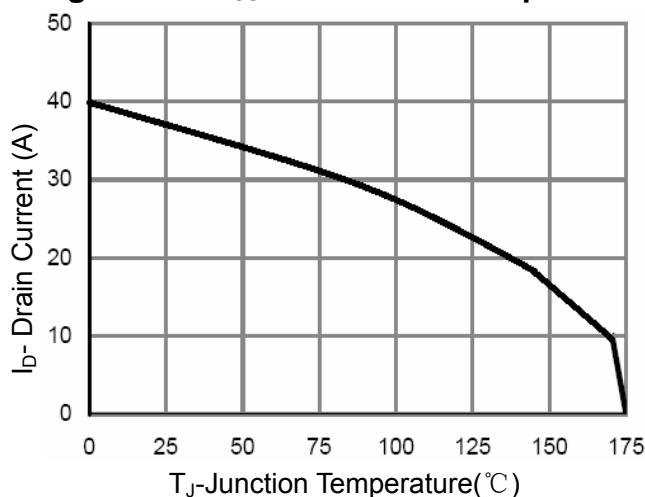
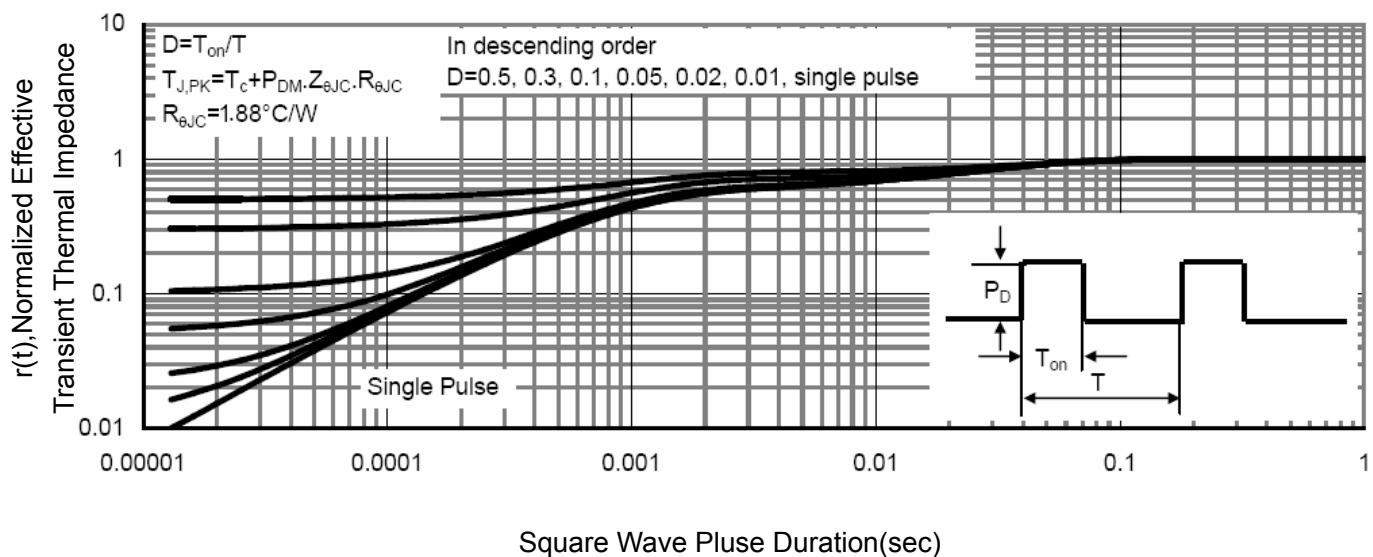
**Figure 4 Rdson-Junction Temperature**



**Figure 5 Gate Charge**



**Figure 6 Source- Drain Diode Forward**


**Figure 7 Capacitance vs Vds**

**Figure 9  $BV_{dss}$  vs Junction Temperature**

**Figure 8 Safe Operation Area**

**Figure 10  $I_d$  Current Derating vs Junction Temperature**

**Figure 11 Normalized Maximum Transient Thermal Impedance**